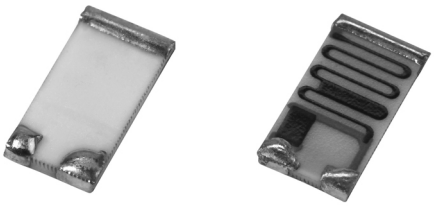
Thick Film Chip Dividers, High Voltage



FEATURES

- High voltage up to 3000 V
- Typical resistance ratios of 250:1, 500:1, etc.
- Flow solderable
- Tape and reel packaging available
- Available with either wraparound terminations or as a single termination flip chip
- Suitable for solderable, epoxy bondable, or wire bondable applications
- Termination: Gold, palladium silver, platinum gold, platinum silver, platinum palladium gold or solder-coated nickel barrier available
- Multiple styles, termination materials and configurations, allow wide design flexibility
- Non-magnetic terminations available
- Compliant to RoHS directive 2002/95/EC
- Halogen-free according to IEC 61249-2-21 definition

Pb-free Available

RoHS* COMPLIANT

HALOGEN FREE

STANDARD ELECTRICAL SPECIFICATIONS

GLOBAL MODEL	POWER RATING $P_{70\ °C}$ W	RESISTANCE RANGE (1) Ω	TOLERANCE (2) ± %	TEMPERATURE COEFFICIENT (3) (- 55 °C to + 150 °C) ± ppm/°C	MAXIMUM WORKING VOLTAGE (4) V	TCR TRACKING ± ppm/°C
CDHV 2512	Contact factory	12M to 1G	1, 2, 5, 10, 20	100	3000	50 (typical)

Notes

(1) Resistance values are calibrated at 100 V_{DC}. Calibration at other voltages available upon request. Contact factory for lower values.

(2) Contact factory for tighter tolerances.

(3) Reference only: Not for all values specified. Consult factory for your value.

(4) Continuous working voltage shall be $\sqrt{P \times R}$ or maximum working voltage, whichever is less.

VOLTAGE AND TEMPERATURE COEFFICIENTS OF RESISTANCE CHART TYPICAL

RESISTANCE (Ω)	RATIO (typical)	VCR (ppm/V)	TCR (ppm/°C) - 55 °C to + 150 °C
20M	250:1	10	100
150M	300:1	10	150
800M	500:1	10	200

Note

• Contact factory for other ratios.

GLOBAL PART NUMBER INFORMATION

New Global Part Numbering: CDHVAF20M0J2500GFB (preferred part number format)

C	D	H	V	A	F	2	0	M	0	J	2	5	0	0	G	F	B

GLOBAL MODEL	TERM STYLE	TERM MATERIAL	RESISTANCE VALUE (R1)	TOLERANCE	RATIO R1/R2	RATIO TOLERANCE	SOLDER TERMINATION	PACKAGING
CDHV = CDHV2512	**A** = 3-sided **B** = Top only	**F** = Nickel barrier **A** = Palladium silver **B** = Platinum gold **C** = Gold **D** = Platinum silver **E** = Platinum palladium gold	M = MΩ G = GΩ **20M0** = 20 MΩ **800M** = 800 MΩ **1G00** = 1 GΩ	**F** = ± 1 % **G** = ± 2 % **J** = ± 5 % **K** = ± 10 % **M** = ± 20 %	3 digit significant figure, followed by a multiplier **2500** = 250:1 **3000** = 300:1 **5000** = 500:1	**G** = ± 2 % **H** = ± 3 % **J** = ± 5 %	**E** = Sn100 **F** = Sn95/Ag5 **N** = No solder **S** = Sn62/Pb36/Ag2 **T** = Sn90/Pb10	**B** = Bulk **T** = Tape and reel **W** = Waffle

Historical Part Numbering: CDHV2512AF2005J2500Ge2 (will continue to be accepted)

CDHV2512	A	F	2005	J	2500	G	e2
HISTORICAL MODEL	TERM STYLE	TERM MATERIAL	RESISTANCE VALUE (R1)	TOLERANCE	RATIO R1/R2	RATIO TOLERANCE	SOLDER TERMINATION

* Pb containing terminations are not RoHS compliant, exemptions may apply

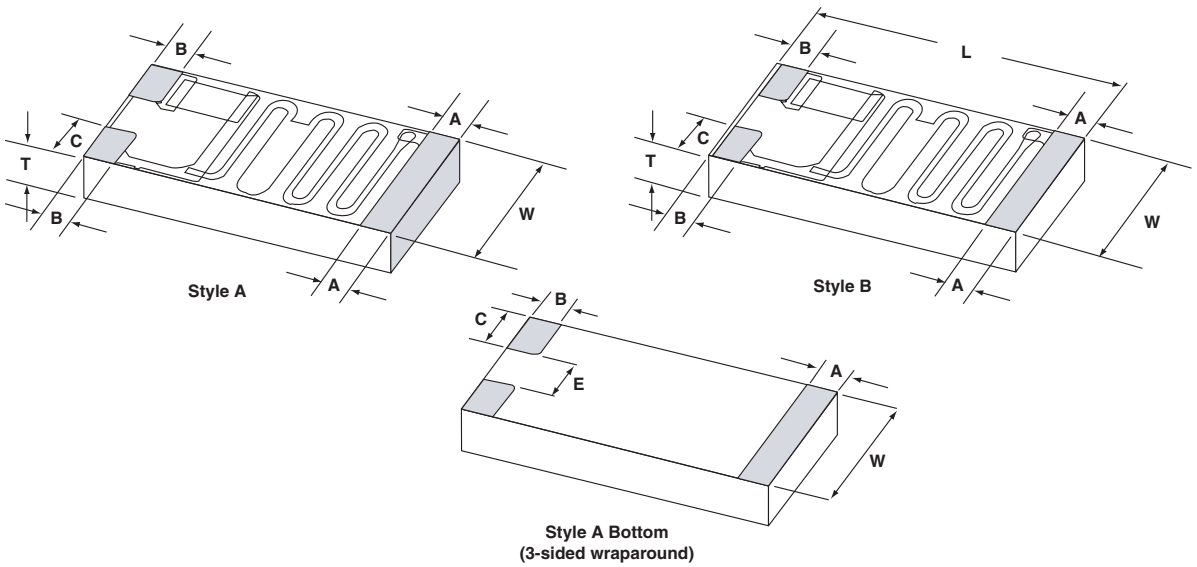
MECHANICAL SPECIFICATIONS	
Resistive element	Ruthenium oxide
Encapsulation	Glass
Substrate	96 % alumina
Termination	Solder-coated nickel barrier standard. Gold, palladium silver, platinum gold, platinum silver, platinum palladium gold terminations available.
Solder finish	Pure tin or tin/lead solder alloys standard. Hot solder dipped tin/silver or tin/lead/silver solder alloys available.

ENVIRONMENTAL SPECIFICATIONS

Operating temperature: - 55 °C to + 150 °C

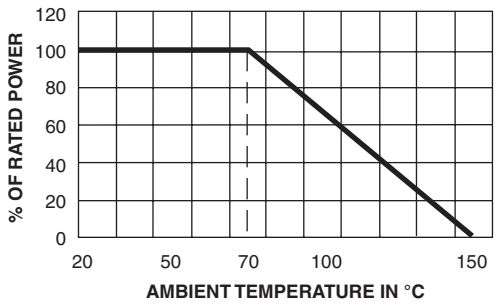
Life: Less than 0.5 % change when tested at full rated power (Reference only: Not for all values specified. Consult factory for your size and value.)

DIMENSIONS in inches (millimeters)



TERMINATION	LENGTH (L) ± 0.006 (0.152)	WIDTH (W) ± 0.006 (0.152)	THICKNESS (T) ± 0.005 (0.127)	A ± 0.005	B ± 0.005	C ± 0.005	E ± 0.005
STYLE A (3-sided wraparound)	0.250	0.126	0.025	0.025	0.025	0.040	0.046
STYLE B (top only)	0.240	0.126	0.025	0.025	0.025	0.040	-

DERATING CURVE



(Reference only: Not for all values specified. Consult factory for your specific value.)

TYPE	TERMINATION MATERIAL	TERMINATION STYLE	TERMINATION STYLE/ MATERIAL CODE	SOLDER TERMINATION CODE
Solderable	Nickel barrier	3-sided (wraparound)	AF	E, F, S or T [3]
		Top only (flip chip)	BF	
Wire bondable/ solderable	Platinum palladium gold	Top only (flip chip)	BE	N, F or S [1]
Wire bondable/ epoxy bondable	Gold	Top only (flip chip)	BC	N
Epoxy bondable	Palladium silver [2]	Top only (flip chip)	BA	N
	Platinum gold		BB	
	Platinum silver		BD	

Notes
[1] Use solder termination N for applications requiring wire bondable mounting, and solder terminations F or S for applications requiring solderable mounting.
[2] While not recommended, palladium silver terminations could be used for solderable applications when using a solder alloy containing silver.
[3] Standard solder plating for the nickel barrier parts are solder terminations E or T. Hot solder dipped terminations F or S are also available.

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